

Value Communications Appliance Reference Design

Product Highlights

Performance Benefits of the Intel® 810 chipset

The Value Communications Appliance Reference Design uses the Intel® 810 chipset, which was built on the foundation of the Intel® 440BX AGPset, and offers similar features and benefits.

The key benefits of using the Intel 810 chipset are the following:

- Doubles the IDE throughput from ATA/33 to ATA/66
- Reduces overall system cost and real estate through smart integration
- The Firmware Hub (FWH) with Random Number Generator (RNG) enables stronger encryption, digital signing and security protocols
- Scalable processor support to address different price/performance needs

Value Communications Appliance Features:

- Scalable performance using Intel Celeron™ (300-566 MHz) to Pentium® III processor (600-700 MHz) in the PGA 370 socket
- Dedicated IDE path with support for ATA/66 to ensure maximum available bandwidth during peak transfers
- 32 MB upgradable to 128 MB SoDIMM SDRAM
- Versatile networking and I/O capabilities:
 - Two Ethernet ports (10/100Base-Tx)
 - Dual USB ports (Revision 1.1)
 - Two Serial ports (RS-232)
 - Parallel port (ECP)
 - FDD port
 - One PCI Mezzanine Card (PMC) standard connector for ease of connectivity to the PCI bus (32 Bit/33 MHz)
- VGA output via Pin Header and small adapter
- Support 4 IDE devices
- Small form factor (8.5 x 5.12 inches)
- Ease of use and stand-alone functionality

This reference design is targeted at the value communications appliance market segment. This market segment includes network attached storage, Web caching, network security, load balancing, Virtual Private network (VNP), VoIP, multi-service access devices (MSAD), and e-commerce appliances that help deliver a new level of services to the network. Communication appliances, which bring rich new services to the network, is the fastest growing segment in communications. The flexibility, scalability, and reliability of the Intel architecture is an ideal platform for new designs that target this fast emerging market segment.

Intel reference design contents

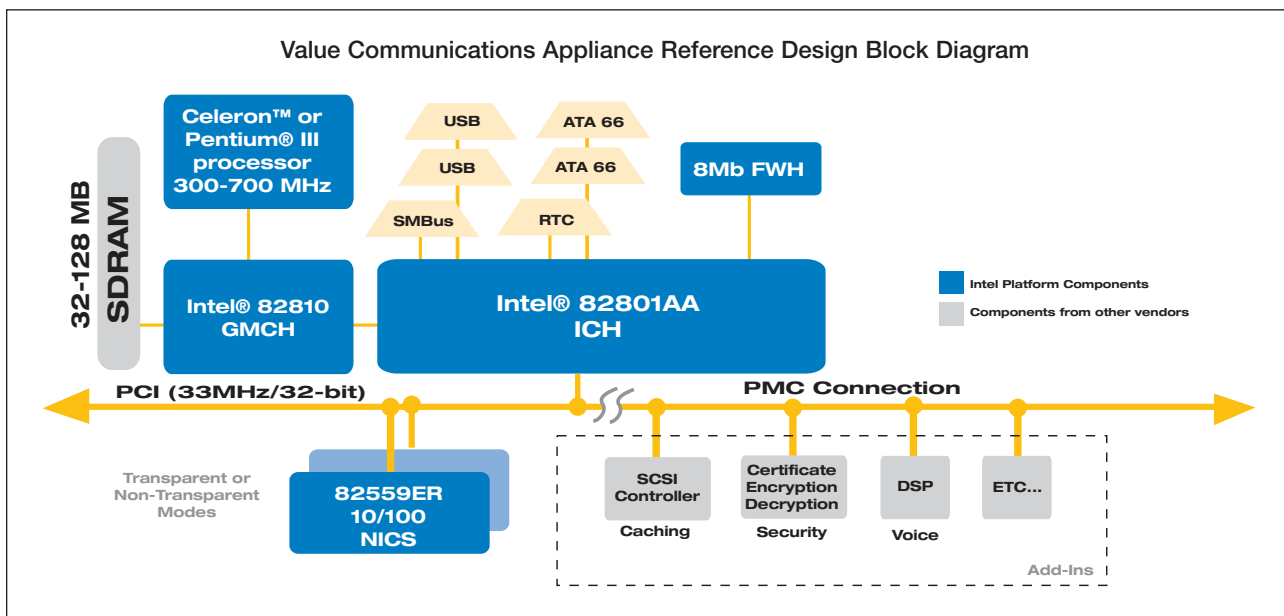
- Orcad V.9 schematics
- Schematics (.pdf format)
- Material list
- Available Original Design Manufacturer list

Product Overview

The Value Communications Appliance Reference Design offered by Intel for embedded applications is a design that contains the essential components for delivering the right performance and functionality for value-based communication appliances. This reference design was developed to enable OEMs focused on the communications appliance market segment to reduce their time to market by delivering a complete design that is easily modified to fit their needs without re-working the core microprocessor and chipset design.

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Third Party Vendor Support

Intel works with multiple independent hardware and software vendors to quickly enable the implementation of designs based on the Value Communication Appliance Reference Design. For more information, visit the Intel website at http://developer.intel.com/platforms/applied/comm/desk_val.htm

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UNITED STATES AND CANADA
Intel Corporation
Robert Noyce Bldg.
2200 Mission College Blvd.
P.O. Box 58119
Santa Clara, CA 95052-8119
USA

EUROPE
Intel Corporation (UK) Ltd.
Pipers Way
Swindon
Wiltshire SN3 1RJ
UK

ASIA-PACIFIC
Intel Semiconductor Ltd.
32/F Two Pacific Place
88 Queensway, Central
Hong Kong, SAR

JAPAN
Intel Kabushiki Kaisha
P.O. Box 115 Tsukuba-gakuen
5-6 Tokodai, Tsukuba-shi
Ibaraki-ken 305
Japan

SOUTH AMERICA
Intel Semicondutores do Brazil
Rue Florida, 1703-2 and CJ22
CEP 04565-001 Sao Paulo-SP
Brazil